



## CALL FOR PAPERS

# Second International Symposium on 3D Power Electronics Integration and Manufacturing

June 25-27, 2018

University of Maryland, College Park, MD

Members of the worldwide electronics community are encouraged to submit abstracts for the second international symposium on 3D Power Electronics Integration and Manufacturing (3D-PEIM). This symposium will bring together practitioners and researchers to share, discuss, and roadmap the latest developments in circuits and systems enabled through advancements in 3D packaging, integration, and manufacturing technologies. The symposium will have a full program of tutorials, invited presentations, contributed papers, interactive sessions, table-top exhibits, and laboratory tours.

**Contributed papers are sought that address important challenges related to the packaging and manufacturing of smaller, lighter, more efficient, and sustainable power electronic products, especially in the following topic areas:**

- Additive Manufacturing
- Embedded Components and Embedding Technologies
- Systems Integration and Thermal Management for High-density Packaging
- Multiphysics Modeling and Simulation of Integrated Packaging and Circuit Solutions
- Materials (e.g., interconnects, encapsulants, substrates)
- Heterogeneous Integration
- Manufacturability of circuits and packaging (manufacturing processes, equipment, and standards)
- Quality and Reliability, including Prognostics and Condition Monitoring

**ABSTRACT FORMAT:** The abstract should consist of two pages of text with sections on the purpose of the study, the approach, and the results and significance, and one page of figures, tables, and references.

**ABSTRACT DEADLINE: DECEMBER 15, 2017**

For more information, please check the Symposium website: [www.3D-PEIM.org](http://www.3D-PEIM.org)

Questions pertaining to the 3D-PEIM Symposium may be addressed to:

General Chair: Prof. Patrick McCluskey, Univ. of Maryland ([mcclupa@umd.edu](mailto:mcclupa@umd.edu))  
Technical Program Chair: Prof. Guo-Quan Lu, Virginia Tech ([gqlu@vt.edu](mailto:gqlu@vt.edu))  
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